

**Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (original) :

A thermal dissipating element of a chip, comprising:

a top plate including a sink ; and

a side plate, said top plate curving and extendedly connecting to said side plate.

Claim 2 (original) :

The thermal dissipating element according to claim 1, wherein said sink contacts with said chip.

Claim 3 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said sink is circular.

Claim 4 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said sink is quadrilateral.

Claim 5 (original) :

The thermal dissipating element according to claim 1, wherein said sink further comprises a lump.

Claim 6 ( currently amended ) :

The thermal dissipating element according to claim 5, wherein said lump contacts with [[a]] said chip.

Claim 7 ( original ) :

The thermal dissipating element according to claim 5, wherein the shape of said lump is quadrilateral.

Claim 8 ( currently amended ) :

The thermal dissipating element according to claim 5, wherein the shape of said lump is selected from quadrilateral or circular.

Claim 9 ( currently amended ) :

The thermal dissipating element according to claim [[1]] 5, wherein said lump is a silicon chip.

Claim 10 ( original ) :

The thermal dissipating element according to claim 1, further comprising a sole plate to extendedly connect to side plate.

Claim 11 ( original ) :

The thermal dissipating element according to claim 10, said side plate and said sole plate including a plurality of holes, said holes being formed between said side plate and said sole plate.

Claim 12 ( original ) :

The thermal dissipating element according to claim 10, wherein said sole plate includes a plurality of cavities.

Claim 13 (original) :

The thermal dissipating element according to claim 5, wherein the material of said lump is metal.

Claim 14 (original) :

The thermal dissipating element according to claim 13, wherein the material of said lump is aluminum.

Claim 15 (original) :

The thermal dissipating element according to claim 13, wherein the material of said lump is copper.

Claim 16 (original) :

A chip packaging element, comprising :

- a substrate ;

- a chip fastened on said substrate ; and

- a thermal dissipating element of said chip, said thermal dissipating element including a top plate, a side plate, and a sole plate, said top plate curving and extendedly connecting to said side plate, said side plate curving and extendedly connecting to said sole plate, said top plate having a sink, wherein said sole plate is fastened on said substrate.

Claim 17 (original) :

The chip packaging element according to claim 16, wherein said sink is fastened on said chip, and said chip is fastened between said sink and said substrate.

Claim 18 (original) :

The chip packaging element according to claim 17, wherein said sink contacts with all of said chip.

Claim 19 (original) :

The chip packaging element according to claim 16, said sink further comprising a lump contacting between said sink and said chip, wherein said chip is fastened between said lump and said substrate.

Claim 20 (original) :

The chip packaging element according to claim 19, wherein said lump is fastened on said sink by an adhesive with high thermal conductivity.